



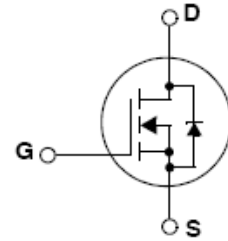
BYD Microelectronics Co., Ltd.

# BF9060BSNL

## 60V N-Channel MOSFET

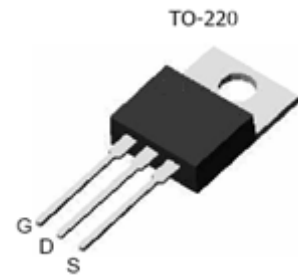
### General Description

This Power MOSFET device has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency, high-frequency isolated DC-DC converters for Telecom and Computer applications. It is also intended for any application with low gate drive requirement.



### Features

- $V_{DS} = 60\text{ V}$
- $I_D = 100\text{ A}$
- Typical  $R_{DS(ON)} = 4.5\text{ m}\Omega$  ( $V_{GS} = 10\text{ V}$ ,  $I_D = 50\text{ A}$ )
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	60	V
$I_D$	Drain Current(continuous)at $T_c = 25^\circ\text{C}$	100	A
$I_{DM}$	Drain Current (pulsed) (Note1)	400	A
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy (Note2)	1900	mJ
$I_{AR}$	Avalanche Current (Note1)	35	A
$P_D$	Power Dissipation ( $T_c = 25^\circ\text{C}$ )	310	W
$T_J, T_{stg}$	Operating junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose	300	$^\circ\text{C}$



## Ordering Information

Part Number	Package	Packaging
BF9060BSNL	TO-220	Tube

## Thermal Data

Symbol	Parameter	Max.	Unit
Rthj-Case	Thermal Resistance Junction-Case	0.4	°C/W
Rthj-Amb	Thermal Resistance Junction-Ambient	60	°C/W

Electrical Characteristics( $T_c = 25^\circ\text{C}$ )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	60			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_c=25^\circ\text{C}$			1	$\mu\text{A}$
		$V_{DS}=60\text{V}$ , $V_{GS}=0\text{V}$ , $T_c=125^\circ\text{C}$			10	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	2.0		4.0	V
$R_{DS(on)}$	Static Drain-Source On Resistance	$V_{GS}=10\text{V}$ , $I_D=50\text{A}$		4.5	7	m $\Omega$
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $f=1\text{MHz}$ , $V_{GS}=0\text{V}$		8144		pF
$C_{oss}$	Output Capacitance			812		pF
$C_{rss}$	Reverse Transfer Capacitance			90		pF
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=30\text{V}$ , $I_D=30\text{A}$ $V_{GS}=10\text{V}$ , $R_G=4.7\Omega$ (Note3, 4)		52		ns
$t_r$	Rise Time			87		ns
$t_{d(off)}$	Turn-Off Delay Time			137		ns
$t_f$	Fall Time			65		ns
$Q_g$	Total Gate Charge	$V_{DS}=48\text{V}$ , $I_D=80\text{A}$ $V_{GS}=4.5\text{V}$ (Note3, 4)		90		nC
$Q_{gs}$	Gate-Source Charge			30		nC
$Q_{gd}$	Gate-Drain Charge			45		nC
$V_{SD(*)}$	Forward On Voltage	$I_{SD}=80\text{A}$ , $V_{GS}=0\text{V}$			1.5	V
$T_{rr}$	Reverse Recovery Time	$V_{DD}=30\text{V}$ , $I_F=100\text{A}$ , $di/dt=100\text{A}/\mu\text{s}$ (Note3)		70		ns

## Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
  2.  $V_{DD} = 30\text{V}$ ,  $L = 2\text{mH}$ , Starting  $T_J = 25^\circ\text{C}$
  3. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
  4. Essentially independent of operating temperature
- (\*) Pulsed: Pulse duration

## Typical characteristics (25°C unless noted)

Figure 1 Output Characteristics

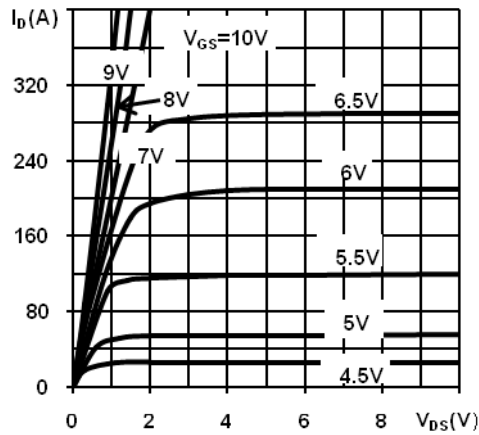


Figure 2 Transfer Characteristics

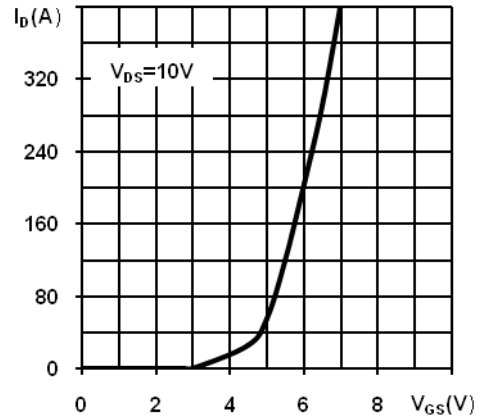


Figure 3 Normalized Threshold Voltage Vs. Temperature

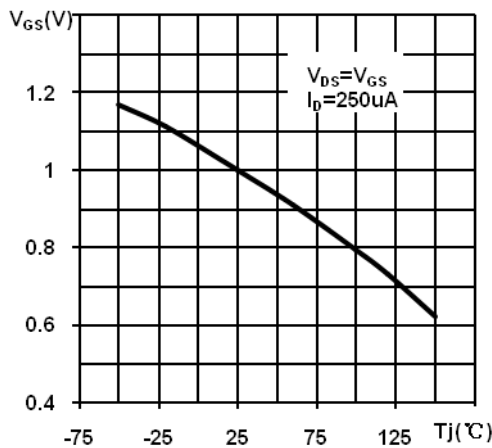


Figure 4 Normalized  $BV_{DSS}$  Vs. Temperature

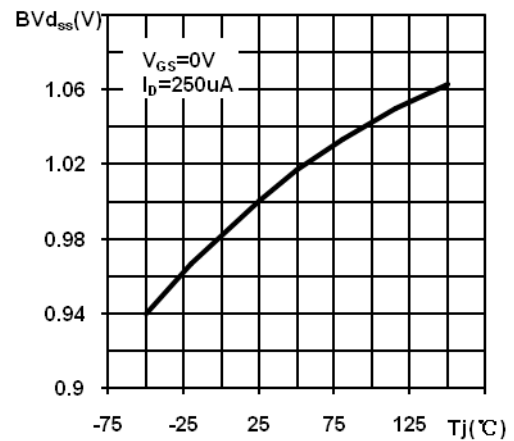


Figure 5 Normalized on Resistance Vs. Temperature

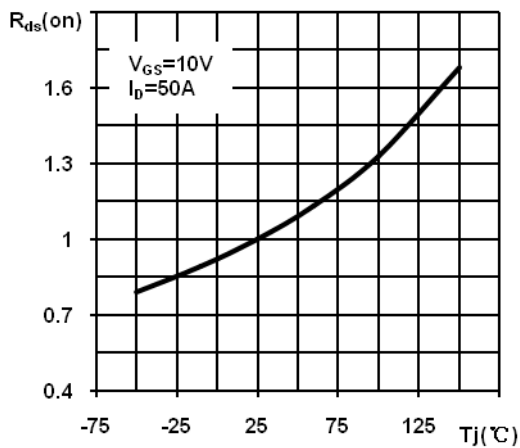


Figure 6 Source-Drain Diode Forward Characteristics

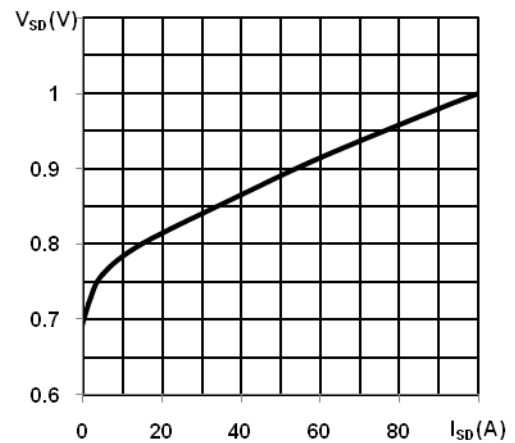


Figure 7 Capacitance

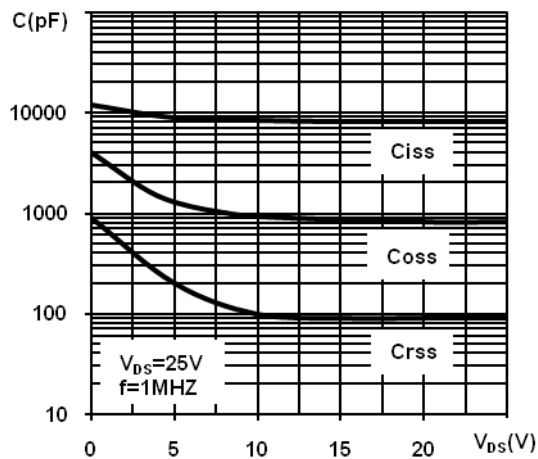


Figure 8 Gate Charge

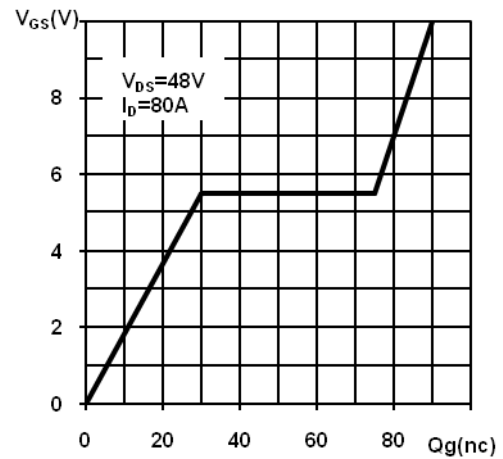


Figure 9 Safe Operating Area

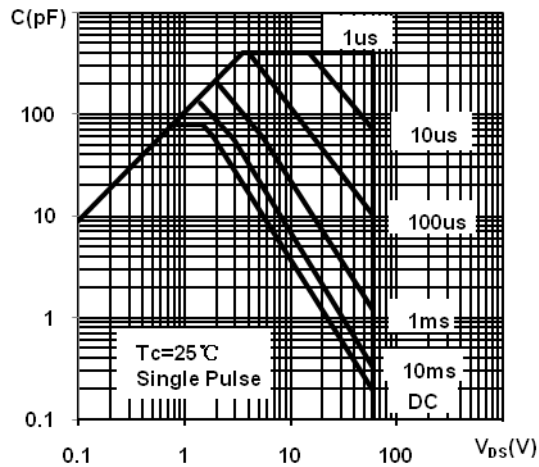


Figure 10 Maximum Drain Current Vs. Case Temperature

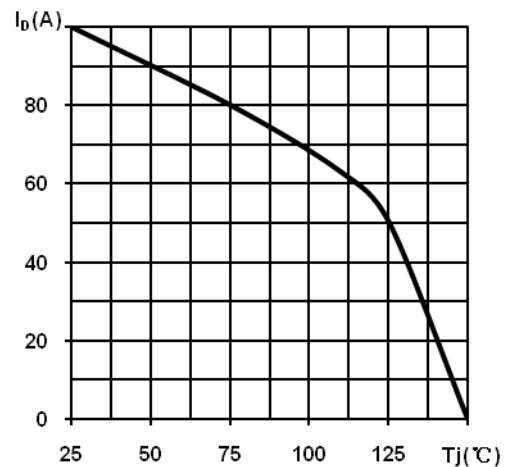
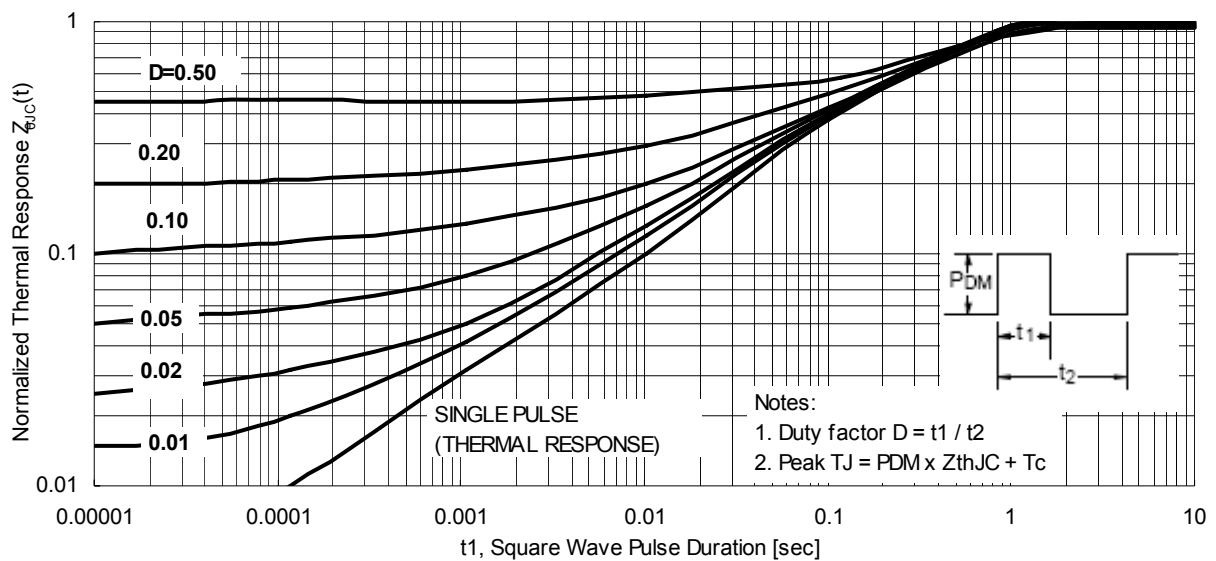
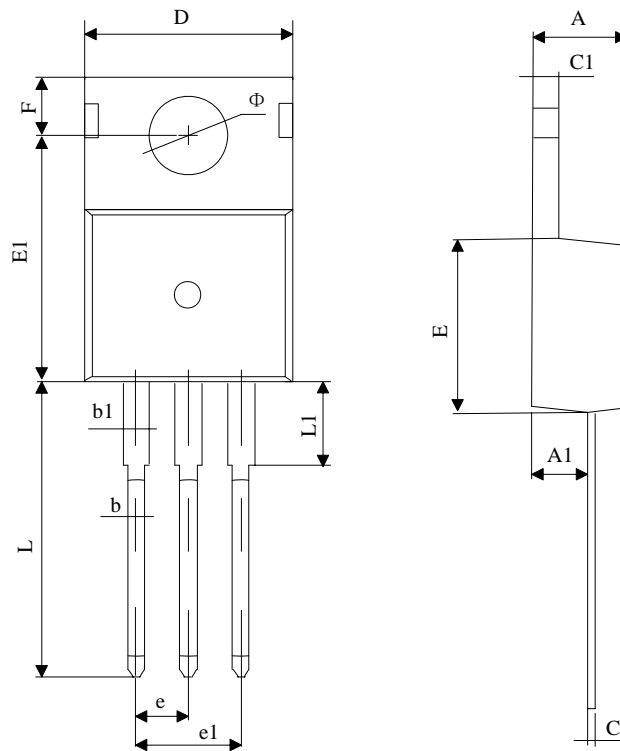


Figure 11 Normalized Maximum Transient Thermal Impedance





## Package Drawing



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.45	4.55	0.175	0.179
A1	2.38	2.42	0.093	0.095
b	0.70	0.90	0.028	0.035
b1	1.42	1.62	0.056	0.064
c	0.45	0.55	0.018	0.022
c1	1.25	1.35	0.049	0.053
D	9.85	9.95	0.388	0.392
E	9.11	9.29	0.359	0.366
E1	12.85	12.95	0.506	0.510
e	2.540TYP		0.100TYP	
e1	5.04	5.12	0.198	0.202
F	2.77	2.83	0.109	0.111
L	12.98	13.18	0.511	0.519
L1	2.97	3.03	0.117	0.119
Φ	3.58	3.62	0.141	0.143



## RESTRICTIONS ON PRODUCT USE

- The information contained herein is subject to change without notice.
- BYD Microelectronics Co., Ltd. (short for BME) exerts the greatest possible effort to ensure high quality and reliability. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing BME products, to comply with the standards of safety in making a safe design for the entire system, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue. In developing your designs, please ensure that BME products are used within specified operating ranges as set forth in the most recent BME products specifications.
- The BME products listed in this document are intended for usage in general electronics applications (personal equipment, office equipment, domestic appliances, etc.). These BME products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of BME products listed in this document shall be made at the customer's own risk.
- BME is not responsible for any problems caused by circuits or diagrams described herein whose related industrial properties, patents, or other rights belong to third parties. The application circuit examples explain typical applications of the products, and do not guarantee the success of any specific mass-production design.